

REMARKS

Claims 1 and 3-5 were pending in the above referenced application. Claims 1 and 3 are amended and Claims 39-48 are added. It follows then that Claims 1, 3-5 and 39-48 are currently pending.

Rejections under 35 U.S.C. §102

Claims 1 and 3-5 stand rejected under 35 U.S.C. §102(e) as being anticipated by Cohen et al. (US 5,800,626) (hereinafter "Cohen"). In addition, Claims 1 and 3-5 stand rejected under 35 U.S.C. §102(e) as being anticipated by Yeol et al. (US 6,039,815) (hereinafter "Yeol"). Applicant traverses both rejections.

For both the rejection under Cohen and Yeol, the Examiner states that:

Claim 1 is positively recited as a method of preparing a liquid. Claim 1 twice refers to a polishing process. However, each reference is merely a statement of a future intended use and such statements are given little patentable weight. (emphasis in original)

Thus while the Examiner admits that neither Cohen nor Yeol teach using a regassified liquid in a polishing process, the "little patentable weight" afforded the Applicant's references to such processing has not served to distinguish Claim 1 from either Cohen or Yeol.

Applicant has amended Claim 1 to add the aspect that the method is for providing a "polishing process liquid." Thus Claim 1 is directed to a method of preparing such a polishing process liquid. Since the Examiner has admitted that neither of the cited references using a regassified liquid in a polishing process and since the polishing process liquid of Claim 1 is such a regassified liquid, it must follow that neither Cohen or Yeol can anticipate Claim 1. Such must also

b true for Claims 3-5 and 39-48, which depend from Claim 1. Ther fore, Applicant respectfully requests withdrawal of the instant rejections and upon such withdrawal, allowance of Claims 1, 3-5 and 39-48.

Applicant respectfully notes that given the absence of any teaching or suggestion in either Cohen or Yeol of any type of polishing process, a rejection of any of the pending claims under §103 for obviousness, based only upon Cohen and/or Yeol, would be inappropriate.

In summary, Applicant having responded to each of the rejections, respectfully asserts that Claims 1, 3-5 and 39-48 are in condition for allowance. Action to that effect is earnestly sought. If, however the Examiner's next action is anything other than a Notice of Allowance, the Examiner is requested to call the undersigned to schedule a telephonic interview. The undersigned is available during normal business hours, Pacific Coast Time.

Respectfully submitted,

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Inventor Dan G. Custer et al.
Assignee Micron Technology, Inc.
Group Art Unit 1746
Examiner A. Olsen
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Title: Polishing Systems, Methods of Polishing Substrates, and Methods of
Preparing Liquids for Semiconductor Fabrication Processes

**VERSION WITH MARKINGS TO SHOW CHANGES MADE ACCOMPANYING
RESPONSE TO OCTOBER 22, 2001 OFFICE ACTION**

The claims have been amended as follows. Underlines indicate insertions
and ~~strikeouts~~ indicate deletions.

1. (Amended) A method of preparing a polishing process liquid for a
semiconductor ~~fabrication~~ polishing process comprising:

providing a liquid;

degassifying the liquid; and

injecting a gas into the liquid to regassify the liquid, the regassification
increasing a total dissolved gas concentration in the liquid to greater than or
equal to 200 ppb, the regassification forming the polishing process liquid, ~~the~~
~~liquid having the increased total dissolved gas concentration for use in the~~
~~polishing process.~~

3. (Amended) The method of claim 1 wherein the providing₇ provides a
water comprising liquid ~~for the semiconductor polishing process.~~

Add new Claims 39-48.